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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: [Approved on 08 August 2023, 13:10 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3%	Gold	7440-57-5	8.5%
			ALUMINIUM	7429-90-5	12%
			Silicon	7440-21-3	79.5%
Die attach	Gold	4%	Tin	7440-31-5	20%
			Gold	7440-57-5	80%
Encapsulation	EP (Epoxy resin)	58.08%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Inner preparation	Gold	0.14%	Gold	7440-57-5	100%
Leadfinish	Tin plating	0.68%	Tin	7440-31-5	100%
Leadframe	Nickel and Nickel alloys	34.1%	Copper	7440-50-8	0.2%
			Silver	7440-22-4	1.2%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.6%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-523	SOD-523	0.015	g